

Pending Active L1: (11885878)c L2: (1186837)carbon L3: (3495969)(tub\$5 post pin needle) L4: (289410) (heatsink (heat thermal\$2) near (sink\$4 spread\$3 dissipat\$3 conducti L5: (287885) power near2 (semiconductor device module element component) L6: (48075)(l\$2) near2 3 L7: (8800) 4 with 5 L9: (4) 8 and 6 L10: (14) "SEMIKRON ELEKTRONIK" as. L11: (1) "DE 10103340" L12: (121) 6 with 4 L13: (5) 8 and 2 L8: (181) 7 with 3 Failed Saved (1) 09/948877 (1736) "KONINKLIJKE PHILIPS" as. (1) 10/682110 (1) 10/684310 (15394) (nano quantum submicron sub adj micron) adj (wire tube rod dot) structure (2506846) tub\$5 post (1168405) carbon (333785) (heatsink (heat thermal\$2) near (sink\$4 spread\$3 dissipat\$3 conducting c (1992139) (microchip micro adi chio chio integrated adj circuit dis ic semiconductor

Aug 2004

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DBs:	USPAT, US_POPUD, EPO, IPO, DIVERVENT, IBM_TOD	<input type="checkbox"/> Plurals <input type="checkbox"/> Highlight all bit terms initially		
Default operator: OR				
7 with 3				

#	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	
	U	I	Y	Document	Issue	P	F	Q	R	S	C	F	S	T	U	V	W	X	Y	Z	P
1	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	Hailbrunner, US 2004010 20040.1: Power semiconductor module	257/708		<input checked="" type="checkbox"/>	US 2004010													
2	<input type="checkbox"/>	<input checked="" type="checkbox"/>	<input type="checkbox"/>	Conte, Rober, US 2004015 20040.1: Pin fin heat sink for power electronic applica	361/709		<input checked="" type="checkbox"/>	US 2004015													
3	<input type="checkbox"/>	<input checked="" type="checkbox"/>	<input type="checkbox"/>	Belady, Chris, US 2004015 20040.9: POWER MODULE FOR MULTI-CHIP PRINTED	361/704-361/715		<input checked="" type="checkbox"/>	US 2004015													
4	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input type="checkbox"/>	Rodrigues, Ju, US 2004014 20040.6: Electric connection arrangement for electron	439/76		<input checked="" type="checkbox"/>	US 2004014													
5	<input type="checkbox"/>	<input checked="" type="checkbox"/>	<input type="checkbox"/>	Wright, Doug, US 2004003 20040.1: Bench top tubing sealer	219/221		<input checked="" type="checkbox"/>	US 2004003													
6	<input type="checkbox"/>	<input checked="" type="checkbox"/>	<input type="checkbox"/>	Sase, Takashi, US 2003023 20031.2: Power-supply device	323/282		<input checked="" type="checkbox"/>	US 2003023													
7	<input type="checkbox"/>	<input checked="" type="checkbox"/>	<input type="checkbox"/>	Weimer, Alan, US 2003018 20031.1: Solar-thermal fluid-wall reaction processing	48/187R-48/118		<input checked="" type="checkbox"/>	US 2003018													
8	<input type="checkbox"/>	<input checked="" type="checkbox"/>	<input type="checkbox"/>	Branch, Scot, US 2003016 20030.1: Modular heat sinks	385/92		<input checked="" type="checkbox"/>	US 2003016													
9	<input type="checkbox"/>	<input checked="" type="checkbox"/>	<input type="checkbox"/>	Tong, Qin-Yi, US 2003014 20030.2: Method of epitaxial-like wafer bonding at lo	257/52	257/686	<input checked="" type="checkbox"/>	US 2003014													
10	<input type="checkbox"/>	<input checked="" type="checkbox"/>	<input type="checkbox"/>	Ko, Cheol So, US 2002008 20020.1: Thermoelectric cooler	623/7	165/104.21	<input checked="" type="checkbox"/>	US 2002008													

Ready

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